

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application. An identifier indicating the status of each claim is provided.

Listing of Claims

1. (Currently Amended) A conductive particle comprising:

a resin particle,

a first conductive thin film disposed around said resin particle,

a first resin coating disposed around said first conductive thin film, and

a second conductive thin film disposed around said first resin coating,

wherein said resin particle is formed of a resin that is harder than said first resin coating,

wherein said first and second conductive thin films are composed of a nickel coating, and a gold coating formed on the surface of said nickel coating.
2. (Currently Amended) A conductive particle according to claim 1, wherein the thickness of said first resin coating is 1/20 times or more and 6 times or less the diameter of said resin particle, and also the thickness of said first resin coating is 0.1 μm or more.
3. (Original) A conductive particle according to claim 1, wherein the thickness of said second conductive thin film is 0.05 μm or more and 0.3 μm or less.

4. (Original) A conductive particle according to claim 1, wherein a second resin coating is formed around said second conductive thin film.

5. (Canceled)

6. (Canceled)

7. (Currently Amended) A conductive particle according to claim 1,
wherein the sum of the weight of said first conductive thin film and the weight of said second conductive thin film is equal to or more than 40% of the weight of the whole of said conductive particle;

the thickness of said first conductive thin film is $1/100$ or more and $1/2$ or less the diameter of said resin particle; and

~~the thickness of said second conductive thin film is $0.05\mu\text{m}$ or more and $0.3\mu\text{m}$ or less.~~

8. (Original) A conductive particle according to claim 1, wherein at least one convex portion is formed on the surface of said first conductive thin film on the side where said first resin coating has been disposed.

9. (Original) A conductive particle according to claim 8, wherein the average number of said convex portions formed on the surface of said first conductive thin film is five or more.

10. (Previously Presented) A conductive particle according to claim 8, wherein the average height of said convex portions formed on the surface of said first conductive thin film is 0.05 μ m or more.

11. (Original) An adhesive comprising: a binder containing thermoplastic resin, and a conductive particle according to claim 1.

12. (New) A conductive particle comprising:
a resin particle,
a first conductive thin film disposed around said resin particle,
a first resin coating disposed around said first conductive thin film, and
a second conductive thin film disposed around said first resin coating,
wherein said resin particle is formed of a resin that is harder than said first resin coating, and
wherein at least one convex portion is formed on the surface of said first conductive thin film on the side where said first resin coating has been disposed.

13 (New) A conductive particle according to claim 12, wherein the average number of said convex portions formed on the surface of said first conductive thin film is five or more

14. (New) A conductive particle according to claim 12, wherein the average height of said convex portions formed on the surface of said first conductive thin film is 0.05 μ m or more.

15. (New) An adhesive comprising: a binder containing thermoplastic resin, and a
conductive particle according to claim 12.